

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No.	:	10/549356	Confirmation No. 1717
Applicant (s)	:	Baikerikar, et al.	
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Examiner	:	Fletcher III, William P.	
Title	:	ORGANOSILICATE RESIN FORMULATION OF RESIN IN MICROELECTRONIC DEVICES	
Docket No.	:	62657A	
Customer No.	:	00109	

Sir:

**RESPONSE TO RESTRICTION REQUIREMENT**

Responsive to the Restriction Requirement dated December 29, 2009, please amend the claims as detailed hereinafter and reconsider the claims in view of the arguments presented hereinafter.

**Amendment to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1. (Original) A curable organosilicate composition that is usefully employed in the formation of a hardmask, etchstop, antireflective, adhesion promoting, or other layer in the fabrication of electronic devices comprising:
  - (a) an alkoxy or acyloxy silane having at least one group containing ethylenic unsaturation which group is bonded to the silicon atom
  - (b) an alkoxy or acyloxy silane having at least one group containing an aromatic ring which group is bonded to the silicon atom,
  - (c) a latent acid catalyst, and
  - (d) optionally an alkoxy or acyloxy silane having at least one C<sub>1</sub>-C<sub>6</sub> alkyl group bonded to the silicon atom.
2. (Original) The composition of claim 1 wherein the first silane (a) is a vinyl acetoxy silane and the second silane (b) is an arylalkoxysilane.
3. (Original) The composition of claim 1 wherein the combination comprises
  - (a) 50-95 mole percent silanes of the formula